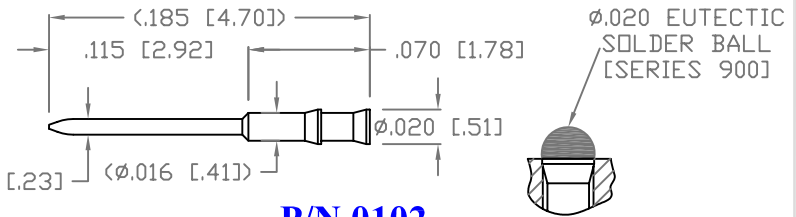
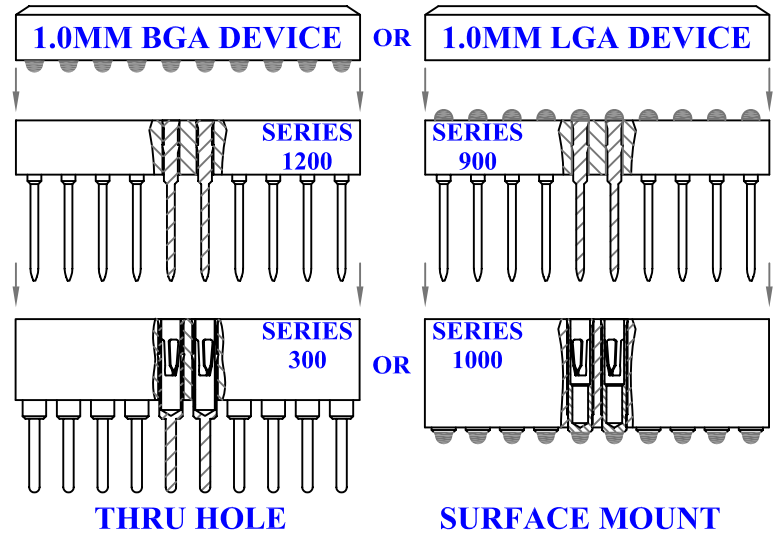
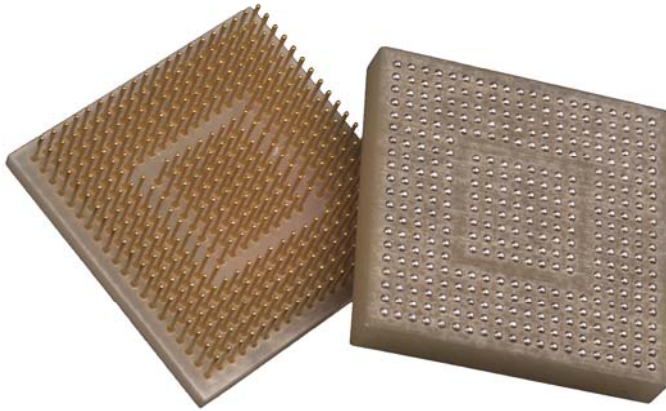


BALL GRID ARRAY SOCKET SYSTEM for .0394 [1.0 MM] ADAPTERS



P/N 0102

Thermal Performance (STANDARD FR-4):

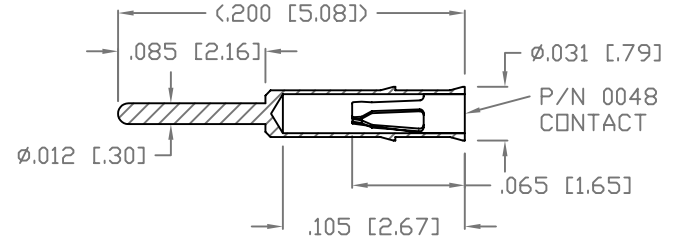
Operating Temperature [range] (To):	-55° to 140° C
Glass Transition Temperature [range] (Tg) :	150° to 200° C
Resistance to Soldering Heat [Thermal Stress]:	10 seconds @ 288° C
Flammability rating:	UL94V-0
IEC Climatic Category:	55 / 125 / 21

Electrical Performance: Tests IAW MIL-STD-202 OR -1344 Methods.

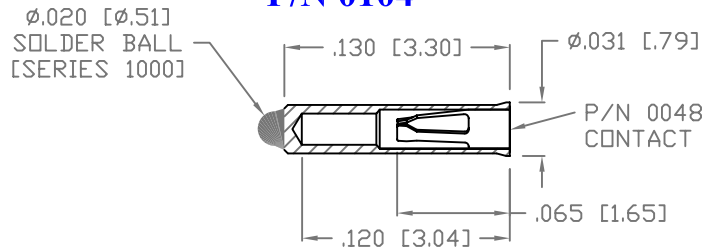
Maximum Voltage:	50VAC/60VDC
Maximum Current:	1 Amperes per contact
Contact Resistance: Dry Circuit:	10 milliohms Max. @ 10 ma / 5VDC
Insulation Resistance, @500VDC:	5,000 MegOhms Min.
Dielectric Withstanding Voltage:	500VAC Min.
Capacitance:	1 pf (PicoFarads) Max.
Self Inductance:	2 nH (NanoHenries) Max.

Contact Materials & Finishes (Other finishes available):

Bodies:	Brass Alloy C36000 per ASTM-B16, 1/2 Hard. Plated 10 uIn. Min. Gold over 50uIn Min. Nickel [Or] 100 uIn. Min. Tin over 50 uIn. Min. Nickel.
Clips:	Beryllium Copper Alloy C17200 per ASTM-B194 Plated 10uIn Min. Gold over 50uIn Min. Nickel
Solder Balls:	63/37 [Sn/Pb] Eutectic Solder, $\phi .020$ Melting Temperature 183°C[361°F]



P/N 0104



P/N 0103

PART NUMBER / ORDER INFORMATION:

300 - 100 F - 0104 - 10A3

PRODUCT CODE PIN COUNT MATERIAL CONTACT P/N PATTERN CODE

300 = SOCKET, PIN GRID ARRAY [PGA]	A = ACRYLIC
900 = LGA INTERPOSER [PGA]	E = PEEK [POLYETHERETHERKETONE]
1000 = SOCKET, BGA [SBGA]	H = POLYIMIDE, [MIL-L-13949/10]
1200 = BGA INTERPOSER [PBGA]	F = FR-4, [IPC-4101/24]
	R = RYTON [POLYPHENYLENE SULFIDE]
	U = G.E. ULTEM [POLYETHERIMIDE]

**01A1 - 99Z9
OVER 24,000
PATTERNS
AVAILABLE**